

# MA370

Silicon epitaxial planer type

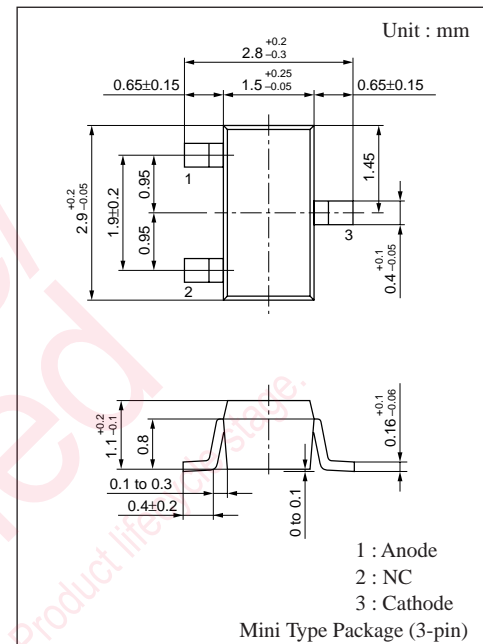
For UHF and SHF electronic tuners

## ■ Features

- Large capacity variation ratio
- Small series resistance  $r_D$
- Mini package, enabling down-sizing of the equipment and automatic insertion through taping and magazine package

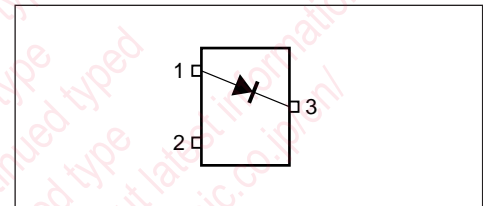
## ■ Absolute Maximum Ratings (Ta= 25°C)

Parameter	Symbol	Rating	Unit
Reverse voltage (DC)	$V_R$	30	V
Peak reverse voltage	$V_{RM}$	32	V
Forward current (DC)	$I_F$	20	mA
Junction temperature	$T_j$	150	°C
Storage temperature	$T_{stg}$	- 55 to +150	°C



Marking Symbol : MZ

## ■ Internal Connection



## ■ Electrical Characteristics (Ta= 25°C)

Parameter	Symbol	Condition	min	typ	max	Unit
Reverse current (DC)	$I_R$	$V_R = 30V$			50	nA
Diode capacitance	$C_{D(1V)}$	$V_R = 1V, f = 1MHz$	3.6	4.6	5.6	pF
	$C_{D(30V)}$	$V_R = 30V, f = 1MHz$	0.5	0.65	0.9	pF
Capacitance ratio	$C_{D(1V)}/C_{D(30V)}$		4			—
Series resistance	$r_D^*$	$C_D = 4.5pF, f = 470MHz$		2		$\Omega$

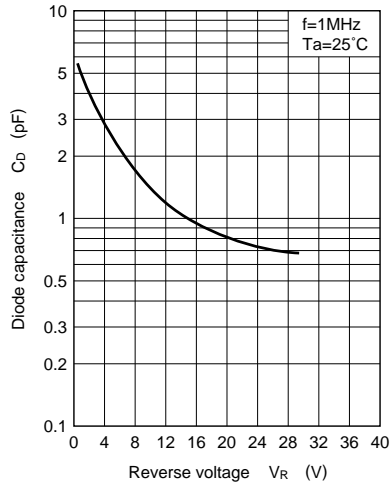
Note 1. Rated input/output frequency : 470MHz

2. \*  $r_D$  measurement device : YHP MODEL 4191A RF IMPEDANCE ANALYZER

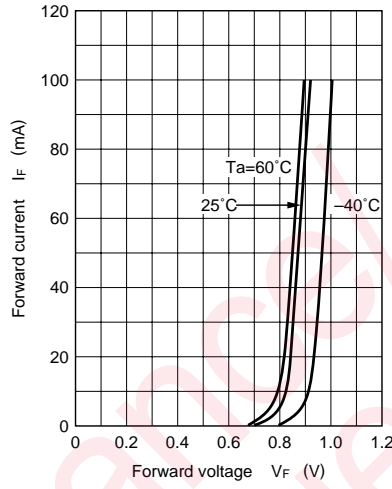
## ■ Marking



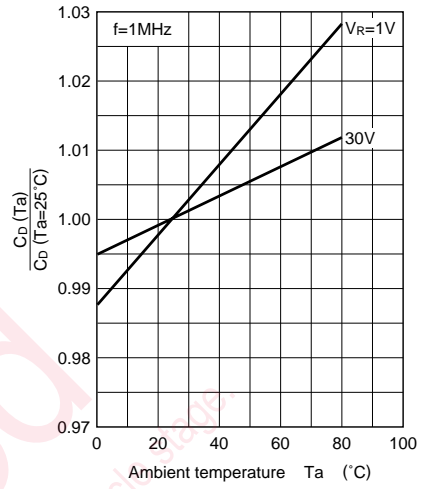
$C_D - V_R$



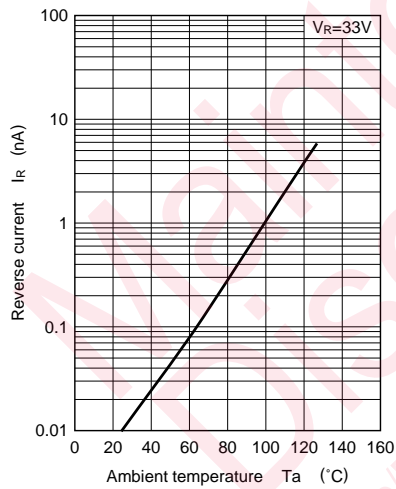
$I_F - V_F$



$C_D - T_a$



$I_R - T_a$



Maintenance/Discontinued includes following four Product lifecycle type  
 planned maintenance type  
 maintenance type  
 planned discontinued type  
 discontinued type  
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